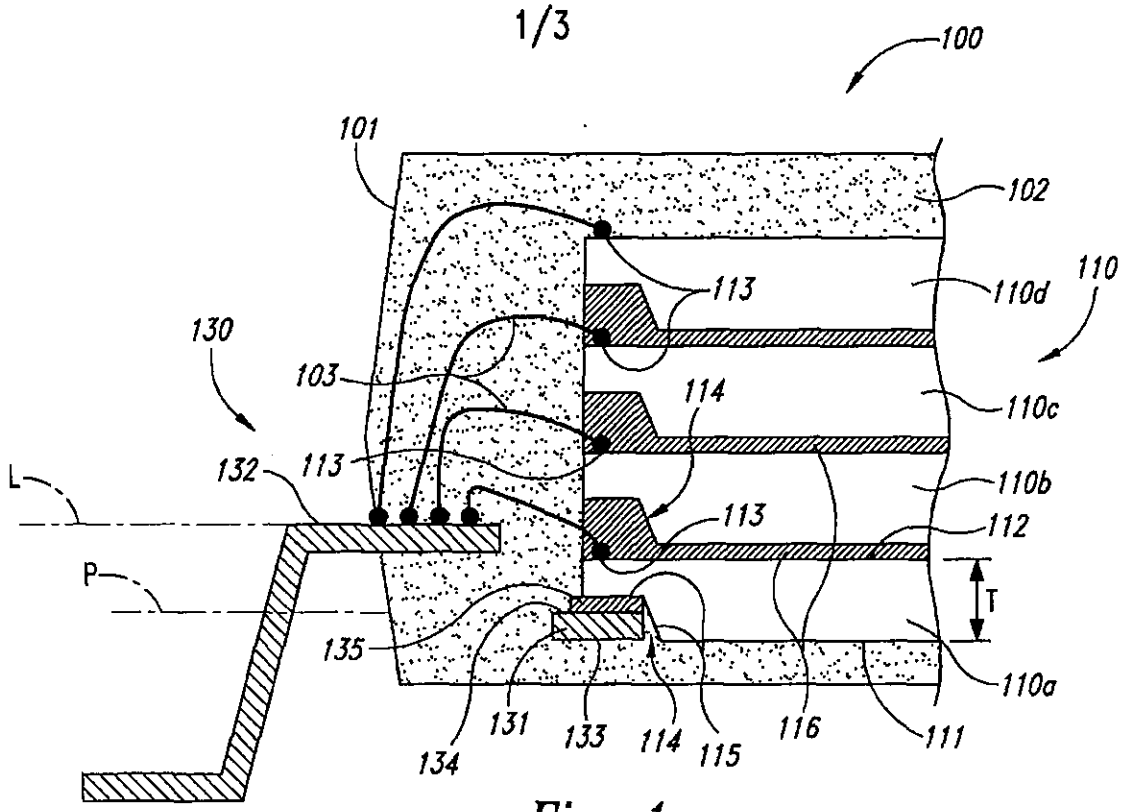

100
101
102
110
113
110d
130
103
114
110c
132
113
110b
L
113
112
P
T
135
110a
131
133
114
115
116
111
134

Fig. 1

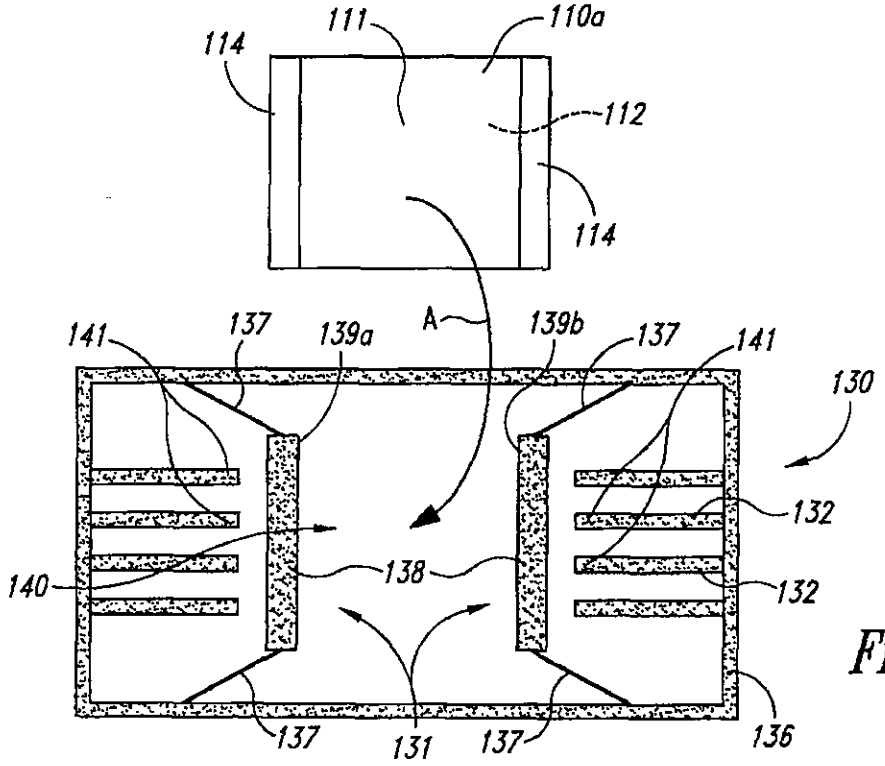

111
110a
114
112
114
A
141
137
139a
139b
137
141
130
132
140
138
132
137
131
137
136

Fig. 2

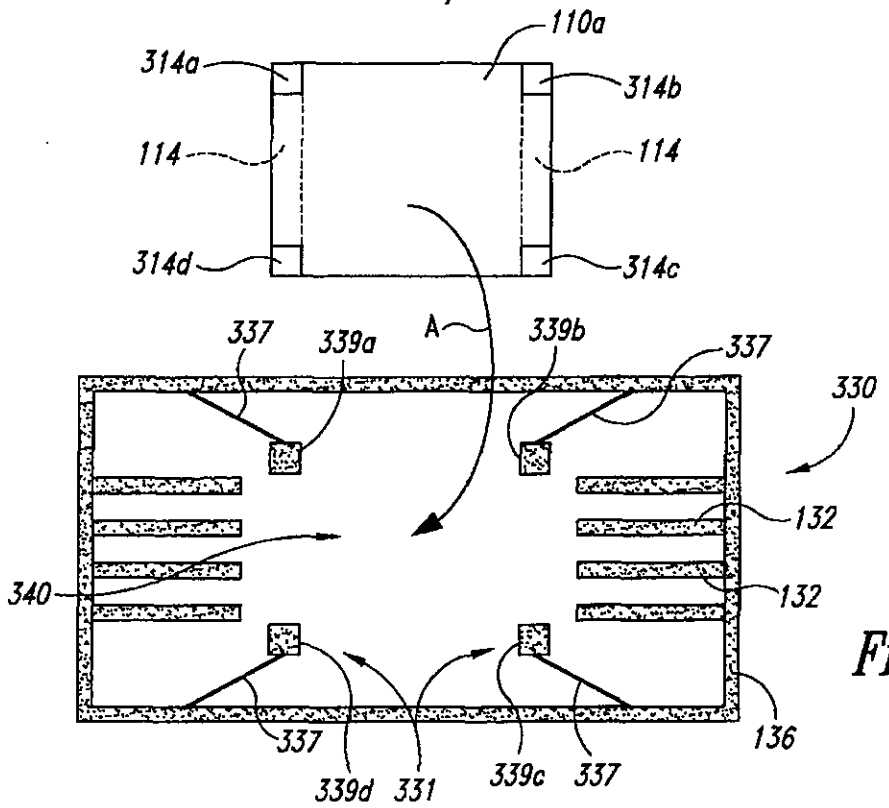

110a
314a
314b
114
114
314d
314c
337
339a
A
339b
337
330
132
340
132
337
339d
331
339c
337
136

Fig. 3

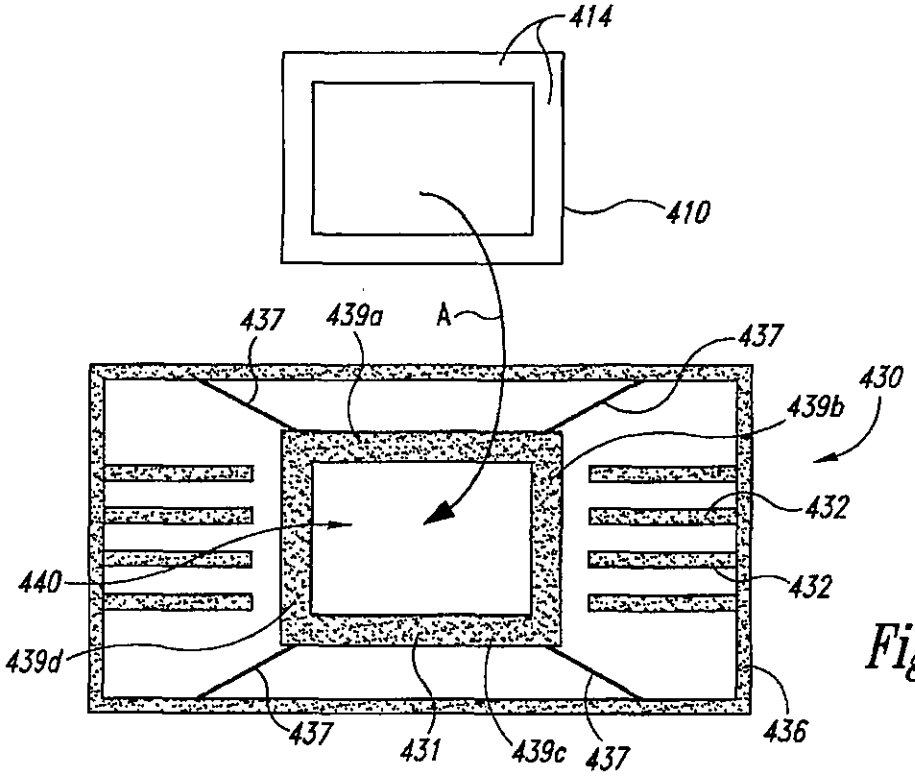

414
410
437
439a
A
437
430
439b
432
440
432
439d
437
431
439c
437
436

Fig. 4

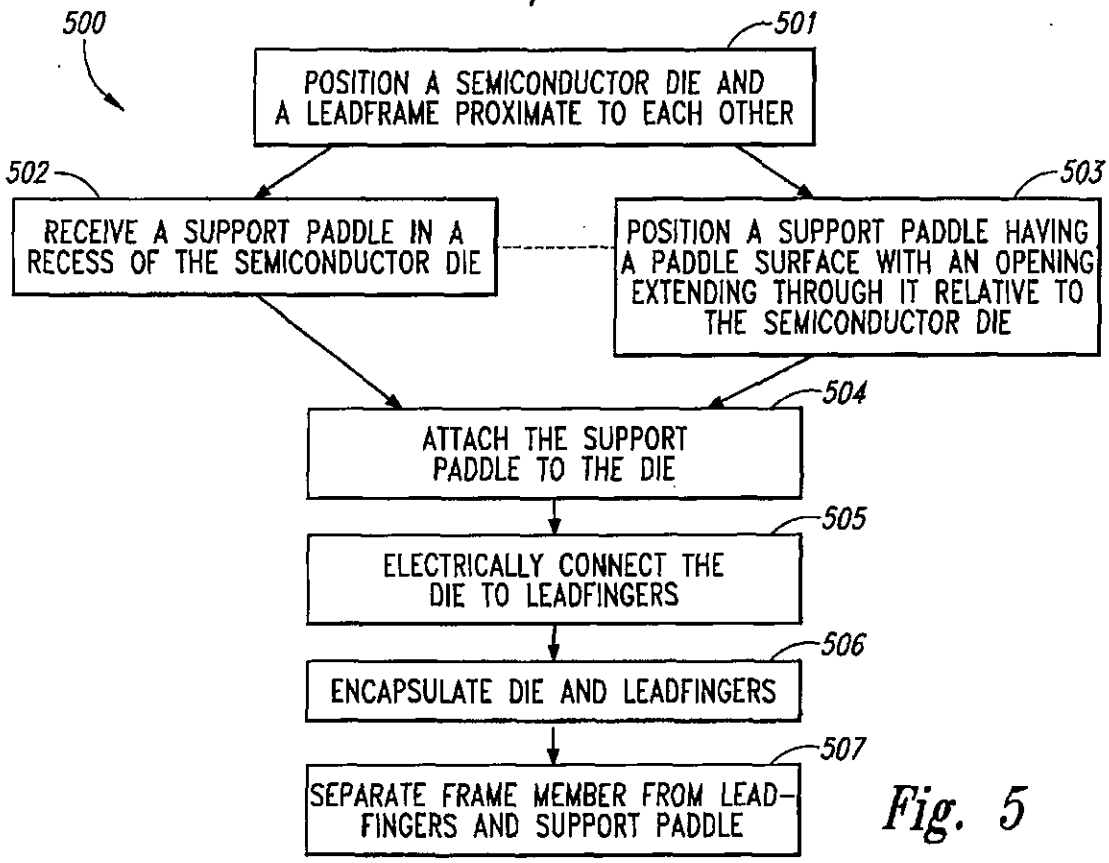

500
501
POSITION A SEMICONDUCTOR DIE AND A LEADFRAME PROXIMATE TO EACH OTHER
502
RECEIVE A SUPPORT PADDLE IN A RECESS OF THE SEMICONDUCTOR DIE
503
POSITION A SUPPORT PADDLE HAVING A PADDLE SURFACE WITH AN OPENING EXTENDING THROUGH IT RELATIVE TO THE SEMICONDUCTOR DIE
504
ATTACH THE SUPPORT PADDLE TO THE DIE
505
ELECTRICALLY CONNECT THE DIE TO LEADFINGERS
506
ENCAPSULATE DIE AND LEADFINGERS
507
SEPARATE FRAME MEMBER FROM LEAD-FINGERS AND SUPPORT PADDLE

Fig. 5

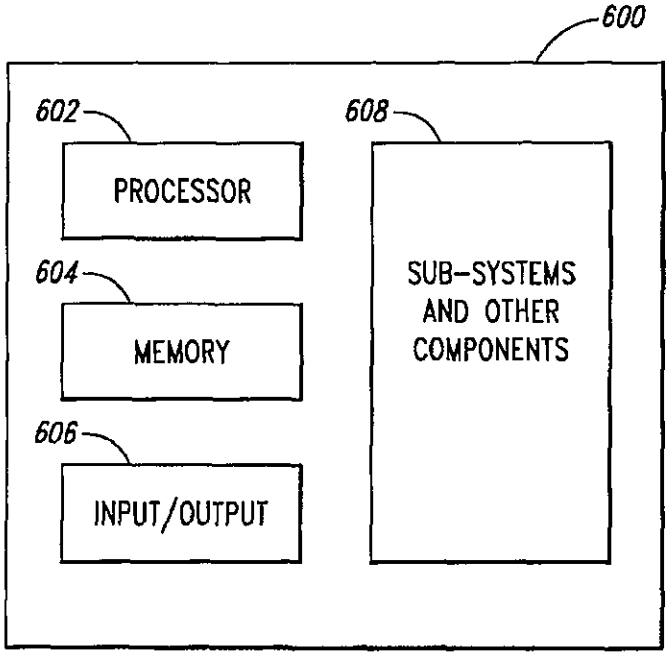

600
602
PROCESSOR
604
MEMORY
606
INPUT/OUTPUT
608
SUB-SYSTEMS AND OTHER COMPONENTS

Fig. 6